

9th TMS Lead Free Solder and Interconnect Technology Workshop

March 3rd, 2013

8:30 am – 5:20 pm

Henry B. Gonzalez Convention Center Room 211

Time	Keynote Speakers	Topic
8:30 – 8:45		- Registration -
8:45 – 9:25	Dr. Ming-Jer Kao	3D IC – Opportunities and Challenges
9:25 – 10:05	Dr. Goyal Deepak	Reliability of Pb-free solder interconnects---the role of defects and their detection
10:05 – 10:25		- Coffee break - (Announcement of poster session)
10:25 – 11:05	Prof. Chin C. Lee	Fundamentals of Fluxless Pb-free Soldering Processes
11:05 – 11:45	Dr. Hiroyuki Ishida	Low-Temperature Wafer Bonding Using Sub-micron Gold Particles for Hermetic Packaging and Interconnection
11:45 – 12:25	Prof. F. P. McCluskey	Lead-free Solder and Die Attach for High Temperature Electronic Packaging
12:25 – 14:00		- Lunch break -
14:00 – 14:40	Prof. Kwang-Lung Lin	Microstructure Evolution of Solder under Electrical Current Stressing
14:40 – 15:20	Dr. Toni T. Mattila	The Failure Mechanism of Recrystallization-Assisted Cracking of Solder Interconnections
15:20 – 16:00	Prof. E. J. Cotts	The dependence of the Sn grain structure of Pb-free solder joints on composition, geometry and thermal history
12:25 – 14:00		- Coffee break -
16:20 – 17:20		- Panel Discussion -

Sponsor

